



NCC AVS CMP USERS GROUP

Cordially invite you to attend its

23rd International Symposium on Chemical-Mechanical Planarization

at High Peaks Resort, Lake Placid, NY

Sunday, August 11 - Wednesday, August 14, 2019

Co-chairs:

S.V. Babu, Clarkson University, US
Andrew Carswell, Micron and CMP Users Group, US
Arthur Chen, NTUST, Taiwan
*Ashwin Chockalingam, Applied Materials
and CMP Users Group, US*
Paul Feeney, Versum Materials and CMP Users Group, US
Hirokuni Hiyama, EBARA, Japan
Taesung Kim, SKKU, Korea

*Dinesh Koli, GLOBALFOUNDRIES and
CMP Users Group, US*
Matt Prince, Intel, US
Raghuveer Patlolla, IBM, US
Michael Pevny, 3M and CMP Users Group, US
Ara Philipossian, University of Arizona, US
Bob Roberts, Axus Technology and CMP Users Group, US
Gerfried Zwicker, Zwicker Consult, Germany

Chemical-Mechanical Planarization has come to occupy a central role in many industrially important technologies. This workshop, to be held in a Gordon conference type format, will focus on several fundamental aspects of chemical-mechanical planarization including:

- *particle and colloidal aspects*
- *polishing mechanisms*
- *pad/conditioning behavior*
- *flow characterization*
- *Cu/barrier film planarization*
- *STI, Nitride/Poly, etc. polishing*
- *defects and post-polish cleaning*
- *low-k films and integration issues*
- *300 mm wafer issues*
- *MEMS/MOEMS*

Invited speakers from end users, equipment and consumable manufacturers, and universities will present their recent research results. As has been the practice in recent years, a poster session will be organized.

For more information contact Leila Boyea, Clarkson University
Phone: 315-268-2336 or Email: leila@clarkson.edu

Click [here](#) for agenda.

Registration fees for the meeting are separate from the Hotel charges and will be collected by the CAMP Office. Personal checks, VISA, Master Card and Discover will be accepted for registration.

Registration link: https://cuonline.clarkson.edu/s/1680/index.aspx?sid=1680&gid=2&pgid=2544&content_id=2482

**University, CAMP Members
& Invited Speakers**

Non-University & Non-CAMP Member

Before	After	Before	After
<u>7/22/19</u>	<u>7/22/19</u>	<u>7/22/19</u>	<u>7/22/19</u>
130.00	230.00	270.00	360.00

One-day registration fee and not staying at the hotel: \$250.00 (including meals and reception).

We are still working on meal information. Anyone not staying at the hotel or not on the meal plan will need to purchase meals separately. I will get the meal information out to everyone as soon as it is available.

Lodging:

Lodging: August is prime summertime in Lake Placid. We have a block of rooms reserved until Wednesday, July 10, 2019. So, please make your reservations early. We must release any unused rooms in our block by July 10. Make reservations with High Peaks Resort by using link [attached hotel reservation form.](#)